



General Features

- High power and current handling capability
- Lead free product is acquired
- Surface mount package

Application

- PWM applications
- Load switch
- Power management

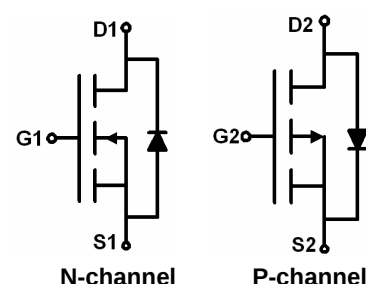
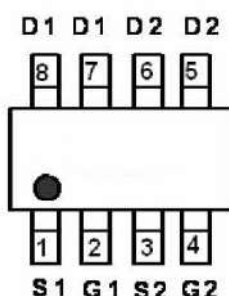
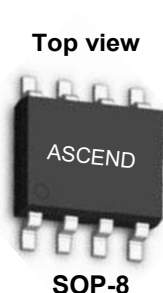
Product Summary

● N-Channel

V_{DS}		30	V
$R_{DS(on),Typ}$	$V_{GS}=10V$	22	$m\Omega$
$R_{DS(on),Typ}$	$V_{GS}=4.5V$	30	$m\Omega$
I_D		8	A

● P-Channel

V_{DS}		-30	V
$R_{DS(on),Typ}$	$V_{GS}=-10V$	43	$m\Omega$
$R_{DS(on),Typ}$	$V_{GS}=-4.5V$	56	$m\Omega$
I_D		-6	A



Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	V_{DS}	30	-30	V
Gate-Source Voltage	V_{GS}	± 20	± 20	V
Continuous Drain Current	I_D	8	-6	A
Pulsed Drain Current (Note 1)	I_{DM}	25	-20	A
Maximum Power Dissipation	P_D	2.5	2.5	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	-55 To 150	$^\circ\text{C}$

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note2)	$R_{\theta JA}$	N-Ch	89	$^\circ\text{C/W}$
		P-Ch	90	

N-CH Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	30	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	<u>V_{DS}=24V, V_{GS}=0V</u> V _{GS} =±20V, V _{DS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}		-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1	1.5	2.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =6A	-	22	29	mΩ
		V _{GS} =4.5V, I _D =4A	-	30	43	mΩ
Forward Transconductance	g _{FS}	V _{DS} =5V, I _D =5A	-	15	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{iss}	V _{DS} =15V, V _{GS} =0V, F=1.0MHz	-	480	-	PF
Output Capacitance	C _{oss}		-	80	-	PF
Reverse Transfer Capacitance	C _{rss}		-	60	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =15V, R _L =3Ω V _{GS} =10V, R _{GEN} =3Ω	-	4.5	-	nS
Turn-on Rise Time	t _r		-	2.5	-	nS
Turn-Off Delay Time	t _{d(off)}		-	14.5	-	nS
Turn-Off Fall Time	t _f		-	3.5	-	nS
Total Gate Charge	Q _g	V _{DS} =15V, I _D =5A, V _{GS} =10V	-	5.2	-	nC
Gate-Source Charge	Q _{gs}		-	0.85	-	nC
Gate-Drain Charge	Q _{gd}		-	1.3	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V, I _S =3A	-	-	1.3	V
Diode Forward Current (Note 2)	I _S		-	-	4	A

P-CH Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-30	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-24V, V _{GS} =0V	-	-	-1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-1	-1.5	-2.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-5A	-	43	52	mΩ
		V _{GS} =-4.5V, I _D =-4A	-	56	77	mΩ
Forward Transconductance	g _{FS}	V _{DS} =-5V, I _D =-4.1A	5.5	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{iss}	V _{DS} =-15V, V _{GS} =0V, F=1.0MHz	-	648	-	PF
Output Capacitance	C _{oss}		-	108	-	PF
Reverse Transfer Capacitance	C _{rss}		-	68	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =-15V, R _L =3.6Ω V _{GS} =-10V, R _{GEN} =3Ω	-	9	-	nS
Turn-on Rise Time	t _r		-	5	-	nS
Turn-Off Delay Time	t _{d(off)}		-	28	-	nS
Turn-Off Fall Time	t _f		-	13.5	-	nS
Total Gate Charge	Q _g	V _{DS} =-15V, I _D =-4A, V _{GS} =-10V	-	14	-	nC
Gate-Source Charge	Q _{gs}		-	3.1	-	nC
Gate-Drain Charge	Q _{gd}		-	3.	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V, I _S =-1A	-	-	-1.3	V

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production

N- Channel Typical Electrical and Thermal Characteristics (Curves)

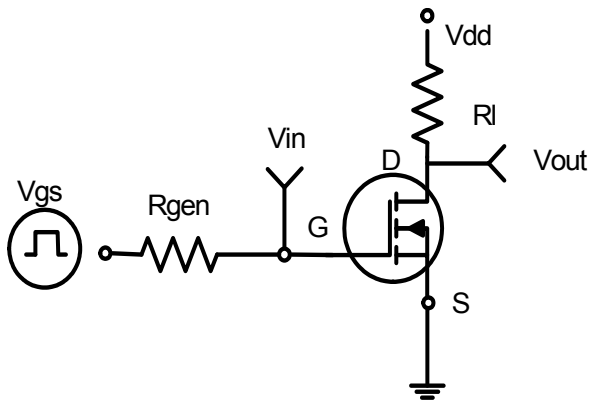


Figure 1: Switching Test Circuit

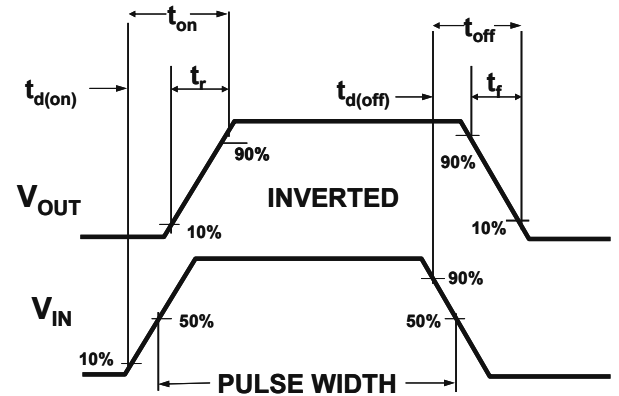


Figure 2: Switching Waveforms

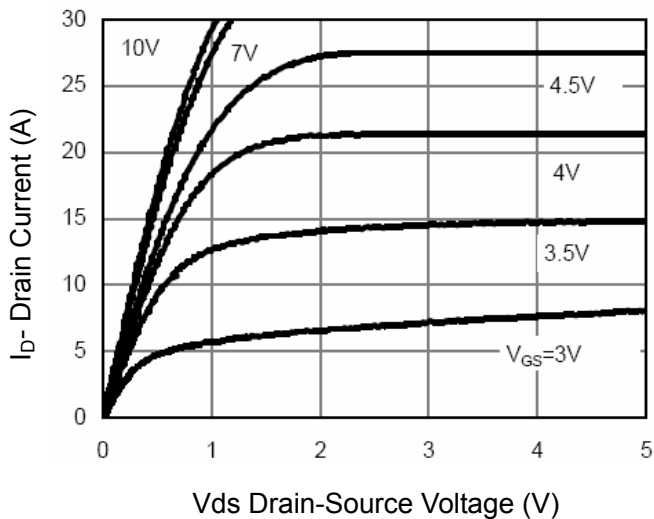


Figure 3 Output Characteristics

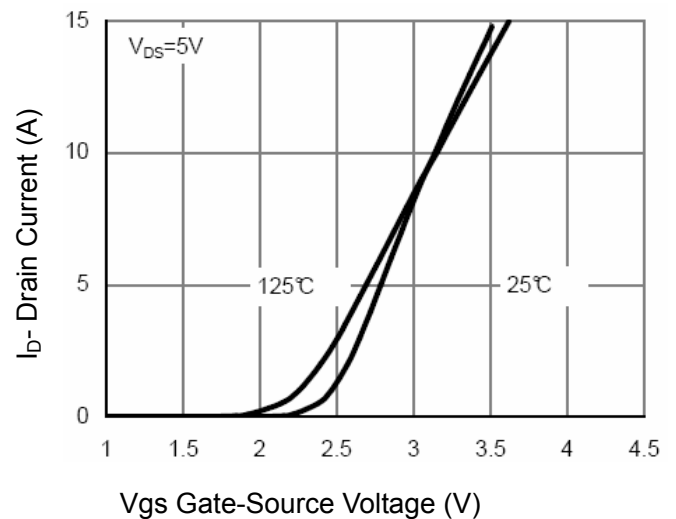


Figure 4 Transfer Characteristics

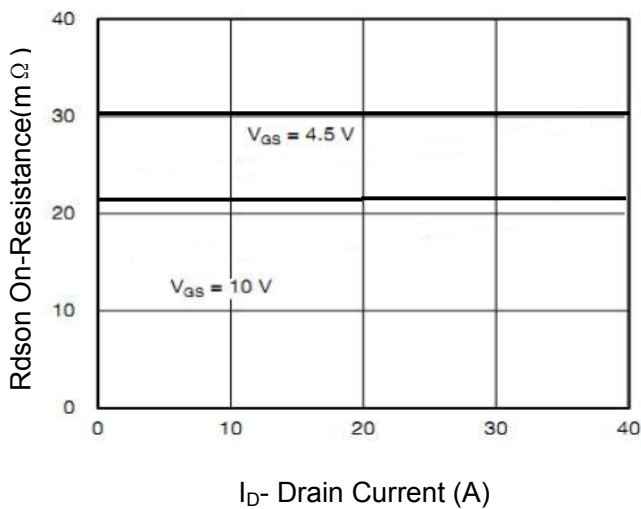


Figure 5 Drain-Source On-Resistance

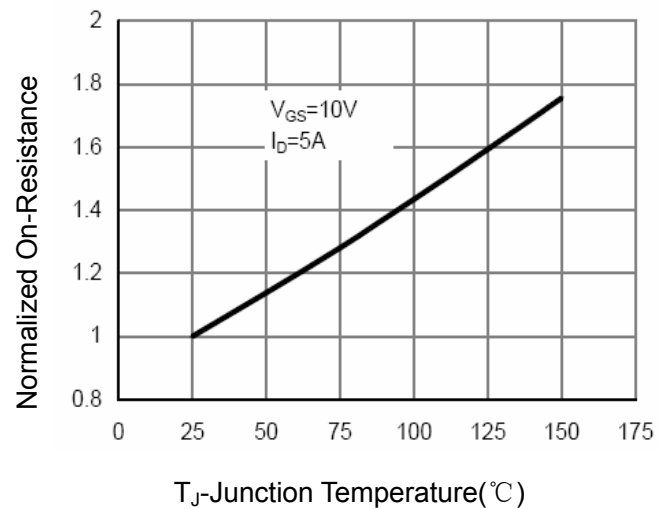
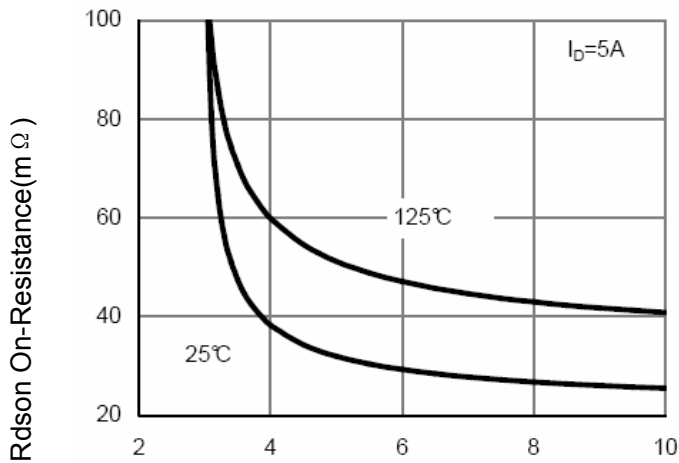


Figure 6 Drain-Source On-Resistance



Vgs Gate-Source Voltage (V)
Figure7 Rdson vs Vgs

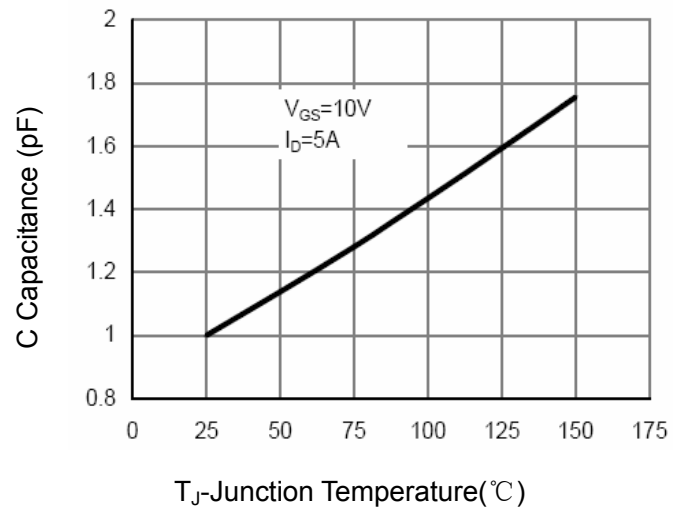


Figure 8 Drain-Source On-Resistance

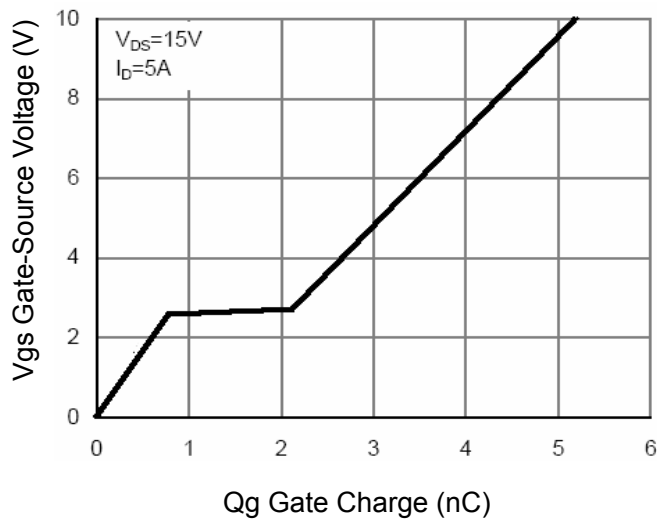


Figure 9 Gate Charge

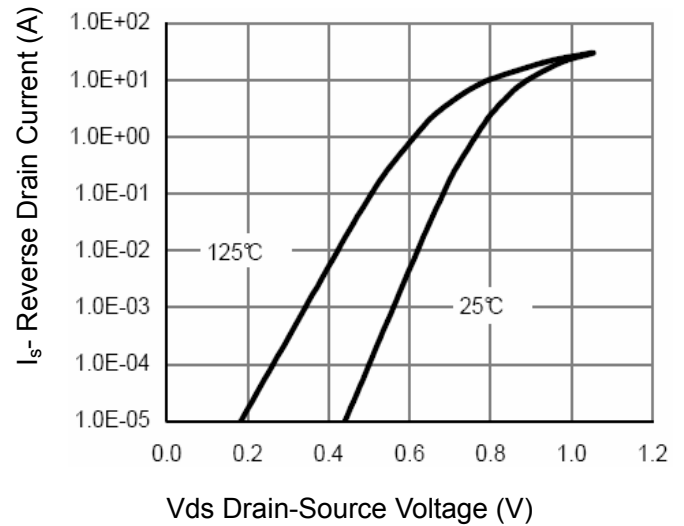
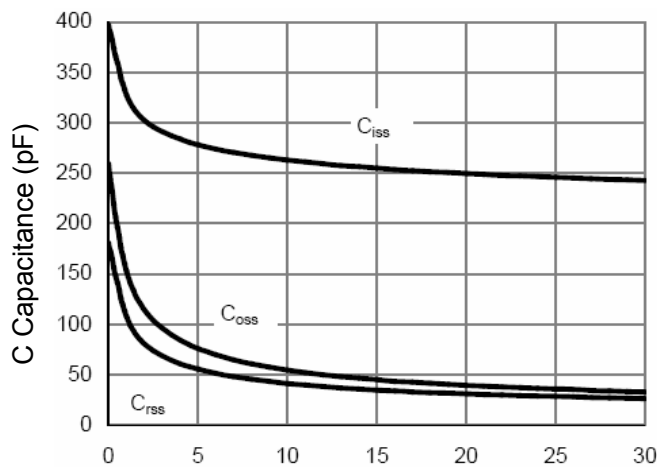
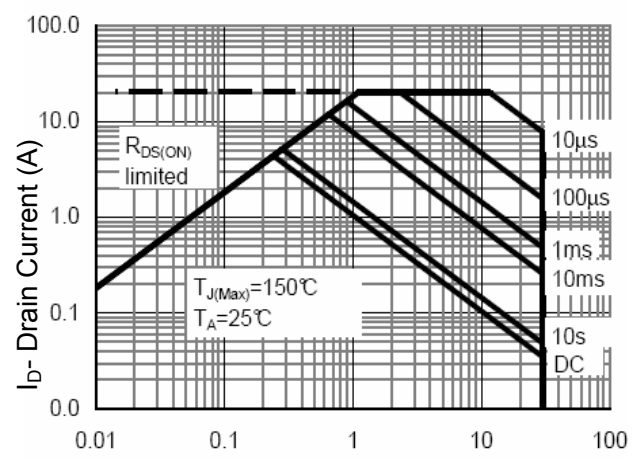


Figure 10 Source- Drain Diode Forward



Vds Drain-Source Voltage (V)
Figure 11 Capacitance vs Vds



Vds Drain-Source Voltage (V)
Figure 12 Safe Operation Area

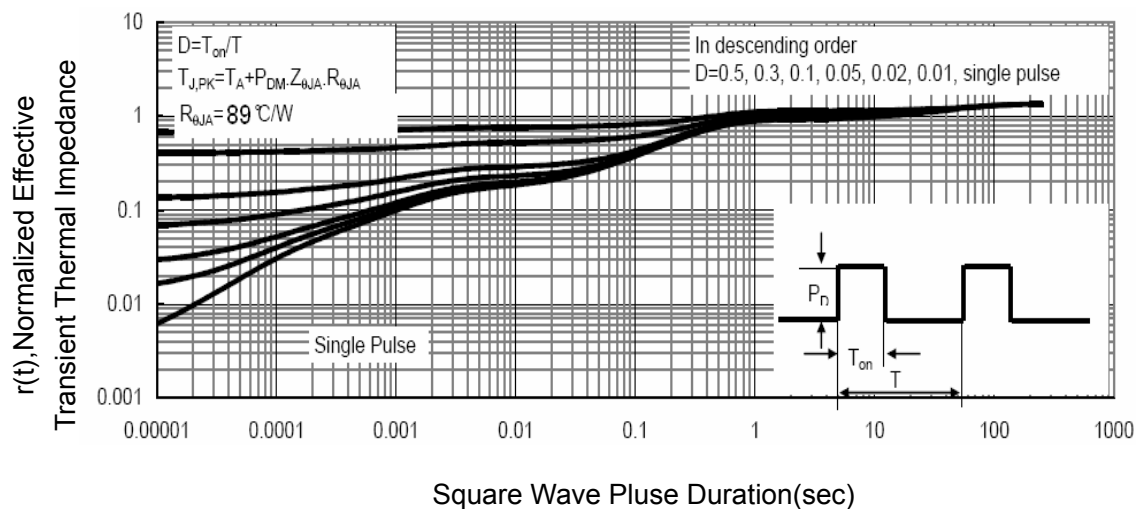


Figure 13 Normalized Maximum Transient Thermal Impedance

P-Channel Typical Electrical and Thermal Characteristics

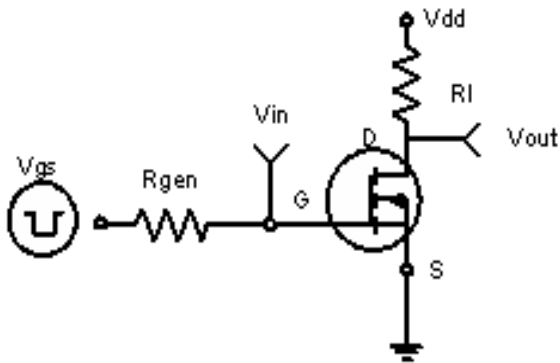


Figure 1: Switching Test Circuit

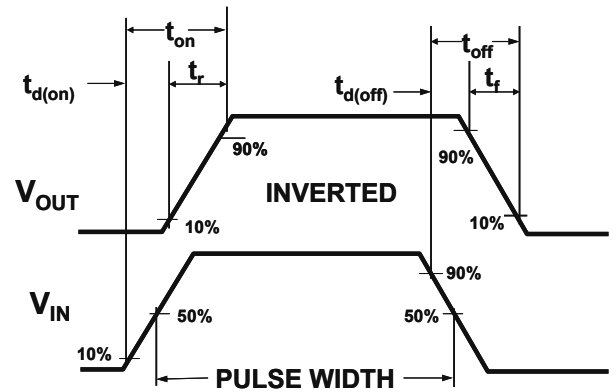


Figure 2: Switching Waveforms

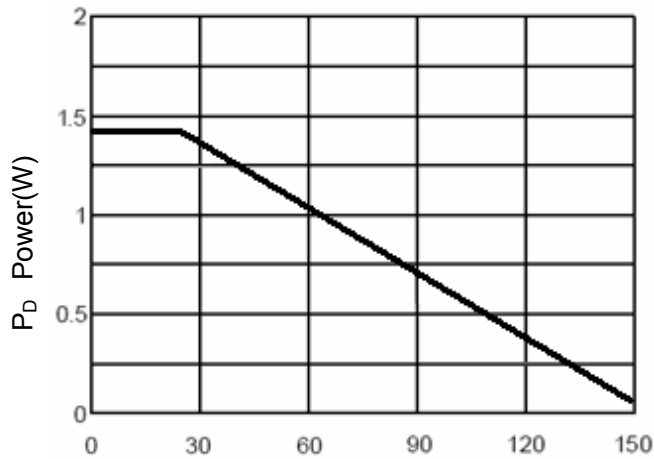


Figure 3 Power Dissipation

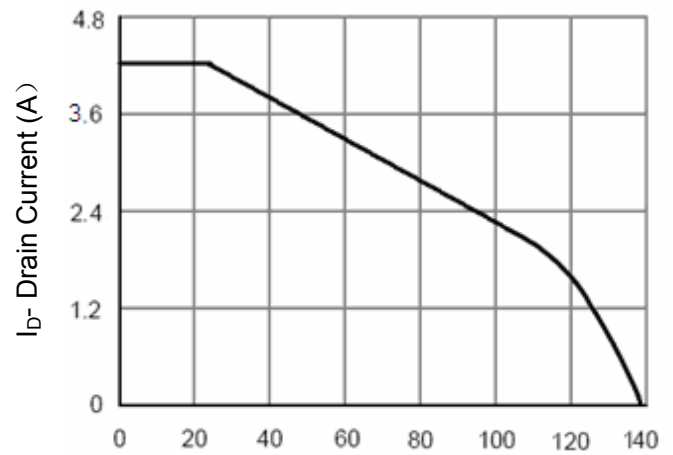


Figure 4 Drain Current

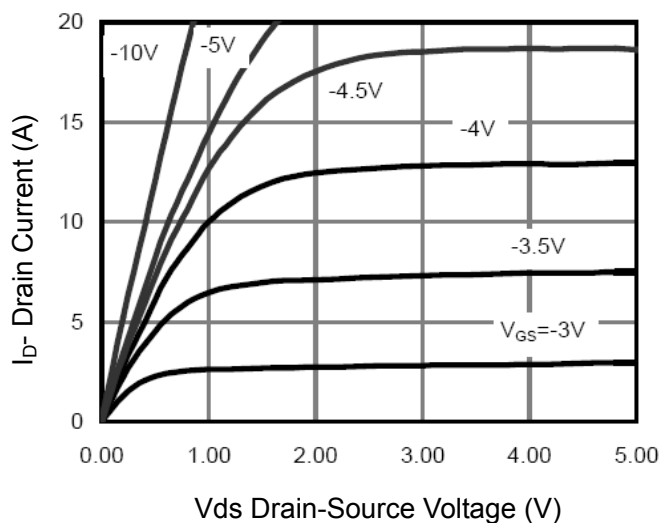


Figure 5 Output CHARACTERISTICS

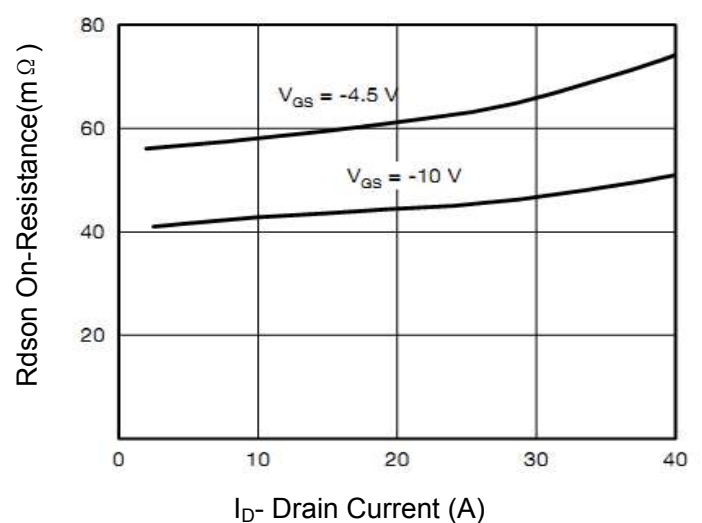


Figure 6 Drain-Source On-Resistance

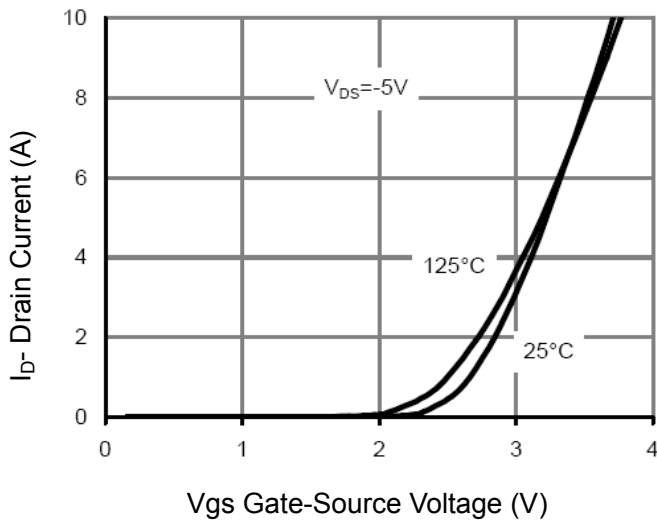


Figure 7 Transfer Characteristics

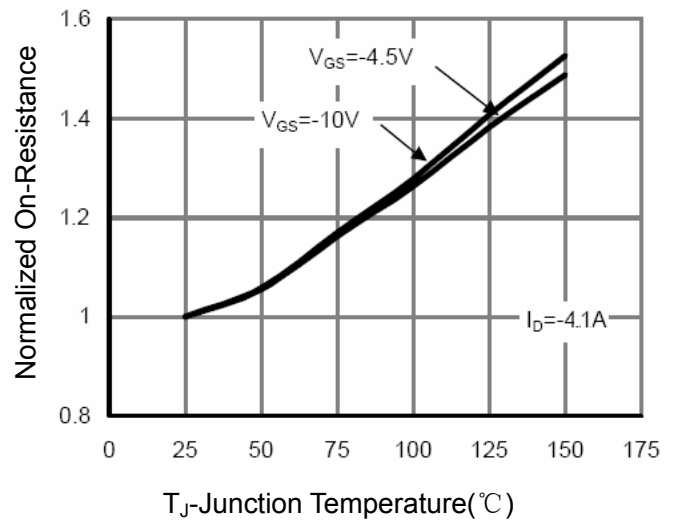


Figure 8 Drain-Source On-Resistance

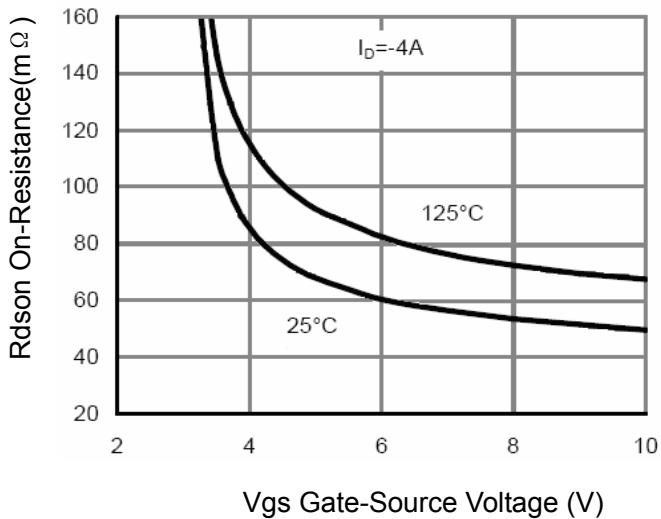


Figure 9 Rdson vs Vgs

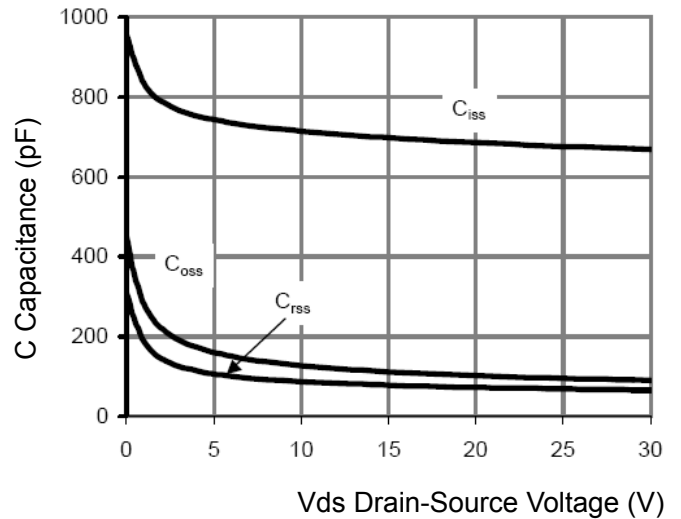


Figure 10 Capacitance vs Vds

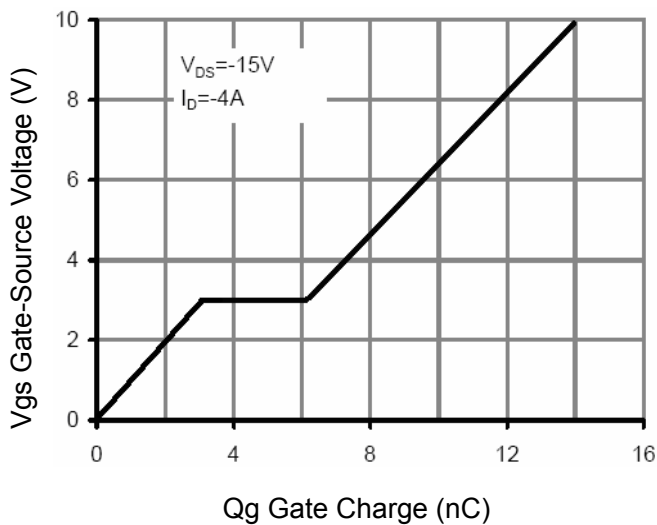


Figure 11 Gate Charge

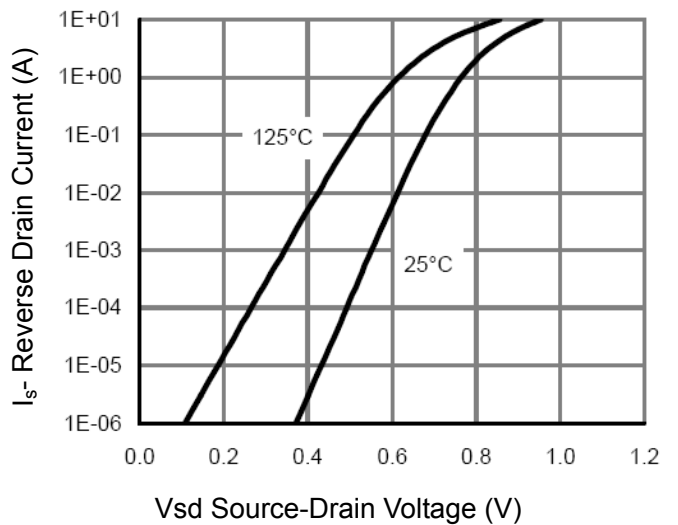


Figure 12 Source- Drain Diode Forward

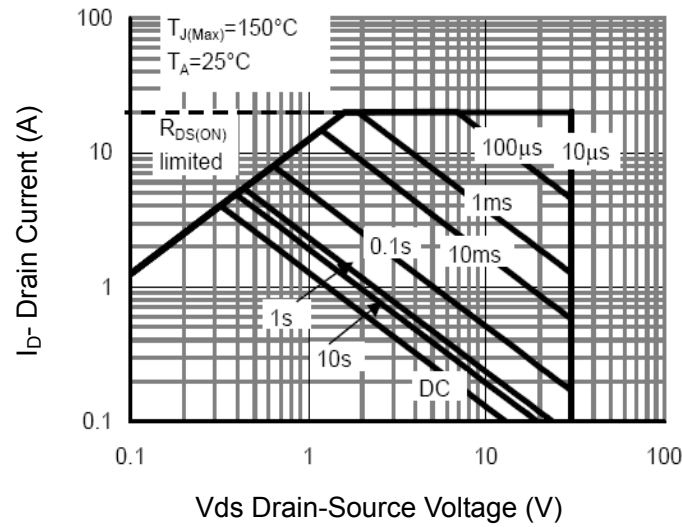


Figure 13 Safe Operation Area

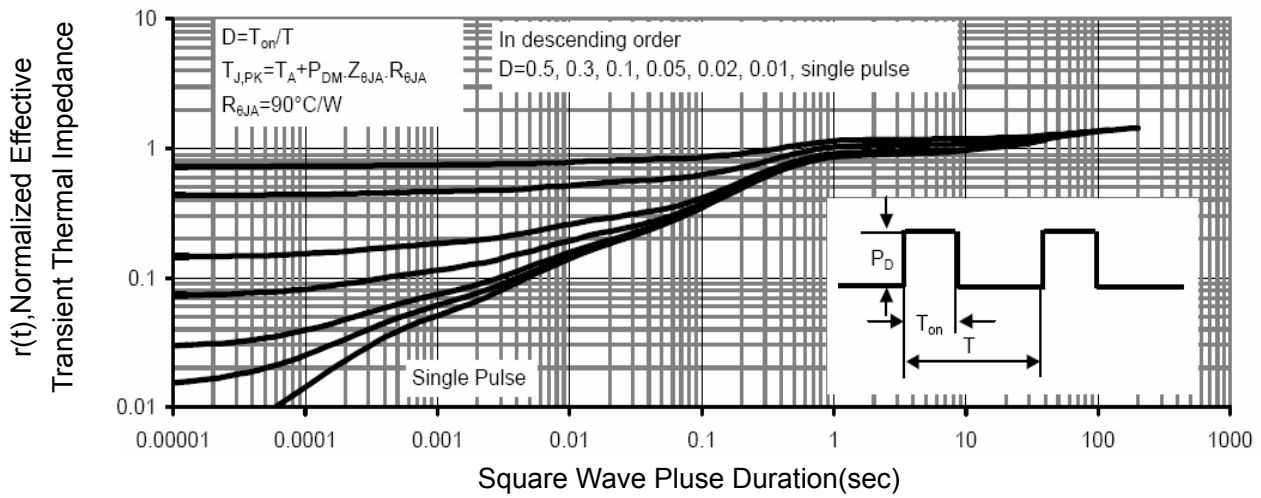
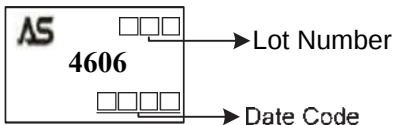


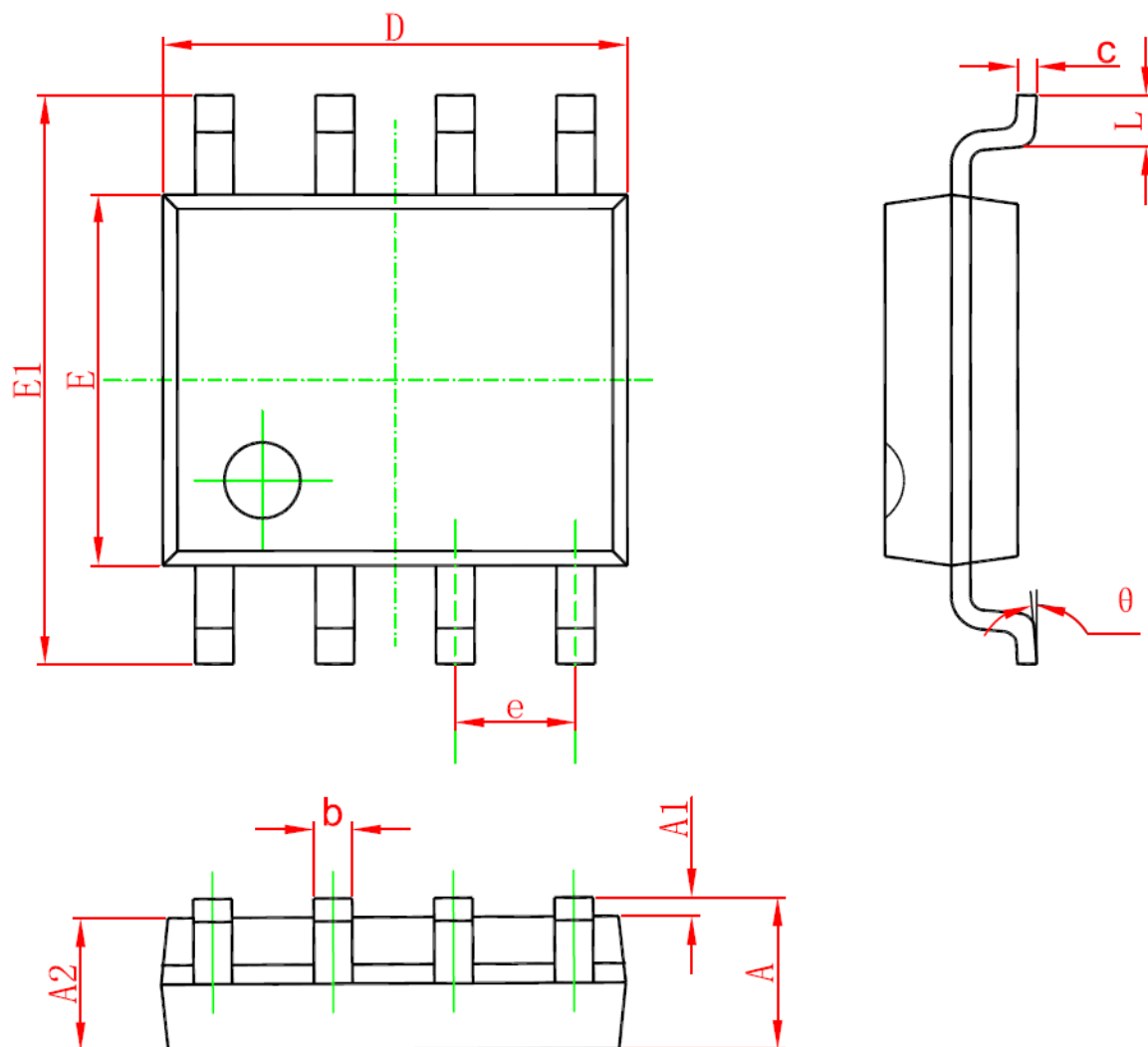
Figure 14 Normalized Maximum Transient Thermal Impedance

Ordering and Marking Information

Ordering Device No.	Marking	Package	Packing	Quantity
ASDM4606S	4606	SOP-8	Tape&Reel	4000/Reel

PACKAGE	MARKING
SOP-8	 AS 4606 Lot Number Date Code

SOP-8 PACKAGE IN FORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

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